

# WSK063

## 半导体晶圆切片机

WSK063 SiC slicing machine (slurry cutting)



### 设备用途和特性

- 本机床适用于半导体行业，用于半导体晶圆的切片。是半导体行业硅片加工的主要配套设备。硅片横断面最大为Φ330mm，切片厚度最小为0.2mm，必须调整制程，一次装夹最大可切片达1300-2300片。是半导体行业硅片生产厂家的优选设备。
- 本机床特点：
  - 1、两个钢线导轮驱动（收/放）线驱动及收/放线的排线驱动，均采用伺服驱动二合一驱动方式。
  - 2、钢线张紧力的检测控制也通过伺服电机驱动（恒应力）。
  - 3、工件进给由伺服电机通过滚珠丝杆拖动，进给量的大小与钢线的引导速度相匹配。
  - 4、切削液的搅拌与输送。切削液管道通过热交换器达到恒温及计量器计量，与切片速率相适应。
  - 5、本机床为高新技术集中的产品。
- the machine is used for cutting semiconductor wafer, which is main matched processing equipment. The max dimension of cross sectionΦ330mm, the minimum thickness of section 0.2mm, adjust process procedure. it may cut 1300-2300 wafers at one clamping. the optimized equipment for semiconductor manufacturers.
- features:
  - two wire guide wheel drive, especially soft drive, capable of all of these servo driven and use a servodrive.
  - detection control of wire tension also be controlled by servo motor (constant stress).
  - workpiece feed is driven by servo motor through ball screw, feed rate is matched with guiding speed of wire.
  - agitation and conveying of cutting fluid. Cutting fluid pipe can reach up, constant temperature through heat exchanger, matching the slicing rate.
  - this machine is an integrated high-tech product.

### Applications and structural features

- the machine is used for cutting semiconductor wafer, which is main matched processing equipment. The max dimension of cross sectionΦ330mm, the minimum thickness of section 0.2mm, adjust process procedure. it may cut 1300-2300 wafers at one clamping. the optimized equipment for semiconductor manufacturers.
- features:
  - two wire guide wheel drive, especially soft drive, capable of all of these servo driven and use a servodrive.
  - detection control of wire tension also be controlled by servo motor (constant stress).
  - workpiece feed is driven by servo motor through ball screw, feed rate is matched with guiding speed of wire.
  - agitation and conveying of cutting fluid. Cutting fluid pipe can reach up, constant temperature through heat exchanger, matching the slicing rate.
  - this machine is an integrated high-tech product.

### 技术规格参数 Specification and Technical Parameters

工作 workpiece	
横断面 cross section	≤Φ330mm
长度 length	2×300mm; 1×600mm
厚度 thickness	≥0.20mm (必须调整制程 must adjust manufacturing process)
切割速率 cutting rate	
线速度 linear velocity	最大 700mm/min (速率可以设定 carset)
快速移动 fast move	200mm/min
工作行程 working stroke	最大 MAX.385mm
钢线 wire	
芯线径 diameter of core wire (external diameter)	0.055-0.400mm
钢线长度 length of wire	按线轮而定 according to wire wheel
钢线方向 direction of wire	前进或后退切割 forward or backward/double directional cutting
预先张力 pre-tension	最大50N (端视钢线直径而定), max 50N (according to diameter of wire)
导线轮 wire wheel	
直径 diameter	Φ192mm
长度 length	662mm
个数 number	3
主电机功率 main motor power	最大, max. 3×30KW.
轴距 (左右) wheelbase (left & right)	540mm
轴距 (上下) wheelbase (up & down)	1250mm
钢线偏向滚轮 offset roller	
直径 diameter	160mm
个数 number	2×3(o)
卷绕线盘 winding coil	
卷绕轴工作高度 working height of winding shaft	1355mm
卷绕线盘 winding coil	WSK027S3-21-301
切削液供应 cutting compound supply	
切削液槽容量 maximum capacity of cutting tank	300L
切削液温度控制器 operating temperature controller	10°C~40°C
冷却水进水口 inlet of cooling water	冷却水进水口 (inlet of cooling water)
冷却水出水口 outlet of cooling water	冷却水出水口 (outlet of cooling water)
电气系统 electrical system	
类型 type	SPS控制 SPC控制 CDC控制 G7刀具控制 HMI触屏控制 G7刀具控制+HMI触屏控制
供货商 supplier	西门子 (Siemens)
操作面板 operation panel	
外观尺寸及总重量 outline dimension and total weight	
长度 length	1470mm
宽度 width	2100mm
高度 height	3500mm
总重量 total weight	约13000kg

由于产品不断创新，本资料仅供参考，如有修改恕不通知，本公司保留最终解释权。

\*As products are improving gradually, the above information is only for reference, any modification without notification, we company reserves the final explanation rights.